

RKD700KJ

Silicon Schottky Barrier Diode for Backflow prevention

REJ03G1301-0100

Rev.1.00

Oct 24, 2005

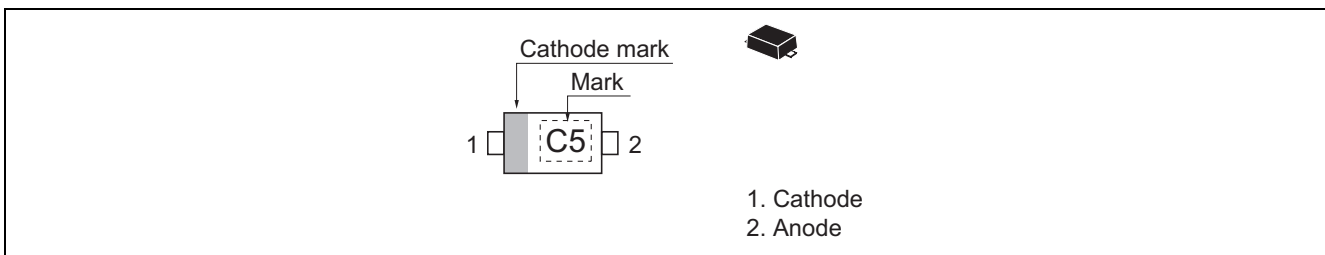
Features

- Low reverse current, Low capacitance.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
RKD700KJ	C5	UFP	PWSF0002ZA-A (UFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V_R	30	V
Non-Repetitive peak forward surge current	I_{FSM}^*	200	mA
Average rectified current	I_O	50	mA
Junction temperature	T_J	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 10 ms Sinewave 1 pulse

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	0.11	0.14	V	$I_F = 1 \mu A$
	V_{F2}	—	—	0.33		$I_F = 1 \text{ mA}$
	V_{F3}	—	—	0.43		$I_F = 10 \text{ mA}$
Reverse current	I_{R1}	—	—	45	nA	$V_R = 3 \text{ V}$
	I_{R2}	—	—	1	μA	$V_R = 30 \text{ V}$
Capacitance	C	—	—	2.8	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Note: 1. For UFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

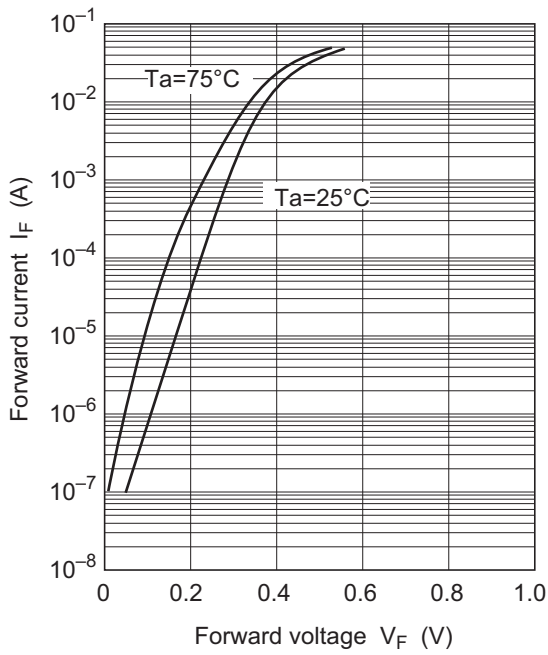


Fig.1 Forward current vs. Forward voltage

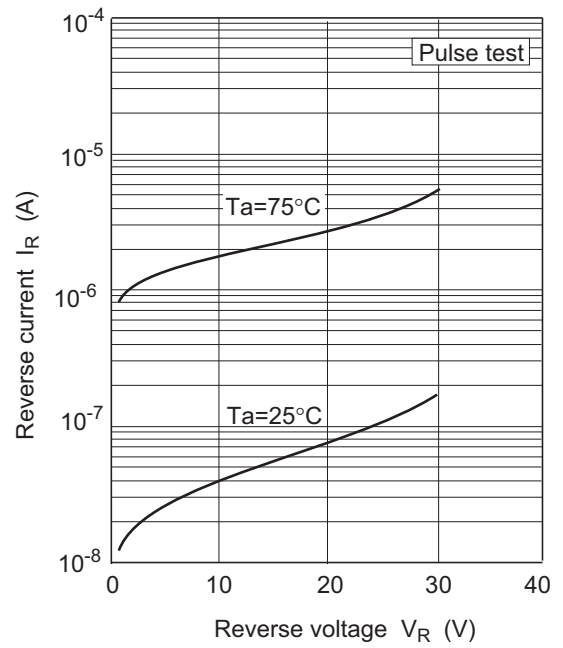


Fig.2 Reverse current vs. Reverse voltage

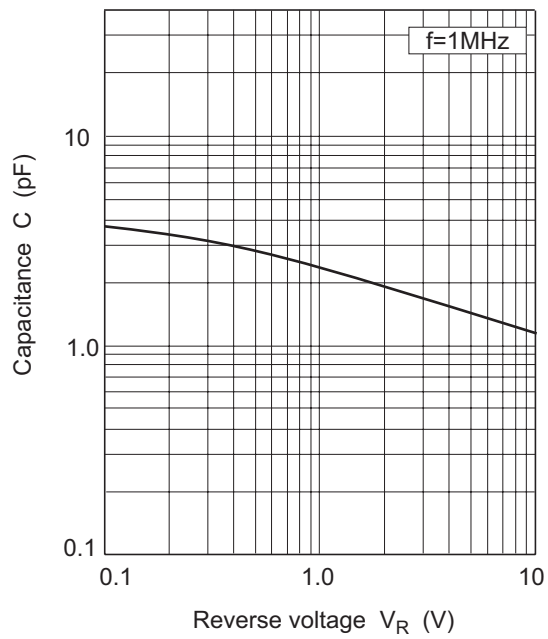
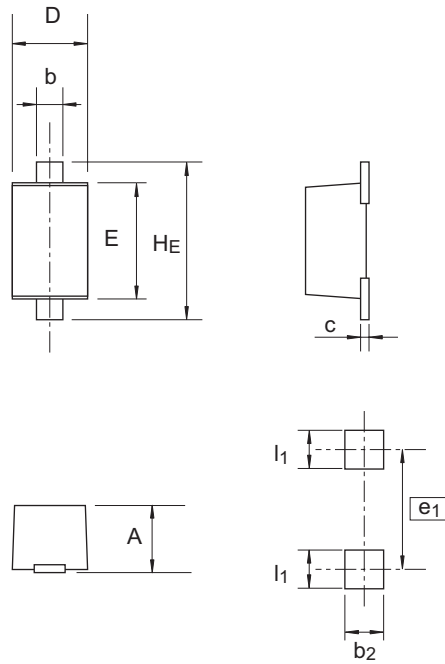


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
UFP	SC-79	PWSF0002ZA-A	UFP / UFPV	0.0016g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.50	0.60	0.70
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.70	0.80	0.90
E	1.10	1.20	1.30
HE	1.50	1.60	1.70
b2	—	0.80	—
e1	—	1.70	—
l1	—	0.60	—

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